

	L #	Hits	Search Text	DBs
1	L1	1	("5822488").PN.	USPAT; US-PGPUB
2	L2	1	("5882488").PN.	USPAT; US-PGPUB
3	L3	0	2 and "227"	USPAT; US-PGPUB
4	L4	1	2 and "727"	USPAT; US-PGPUB
5	L5	11	((("5108951") or ("5693584") or ("5270255") or ("5108570") or ("5288665") or ("5685659") or ("5800182") or ("5443995") or ("4970176") or ("5378660") or ("5371042")).PN.	USPAT; US-PGPUB
6	L6	7	5 and third	USPAT; US-PGPUB
7	L7	29	"5270255"	USPAT; US-PGPUB
8	L8	1	5 and (cap or capping)	USPAT; US-PGPUB
9	L9	219955	cap or capping	USPAT; US-PGPUB
10	L10	181742	9 not (aluminum)	USPAT; US-PGPUB
11	L11	38213	9 not 10	USPAT; US-PGPUB
12	L12	32720	11 not semiconductor	USPAT; US-PGPUB
13	L13	38215	11 not 12	USPAT; US-PGPUB
14	L14	5493	11 not 12	USPAT; US-PGPUB
15	L15	269	14 and (hot and cold)	USPAT; US-PGPUB
16	L16	133	14 and (third near8 temperature)	USPAT; US-PGPUB
17	L17	14	15 and 16	USPAT; US-PGPUB
18	L18	255	15 not 17	USPAT; US-PGPUB
19	L19	48289	438/\$.cccls. or 204/192\$.cccls.	USPAT; US-PGPUB
20	L20	4526	19 and 9	USPAT; US-PGPUB
21	L21	82	20 and (hot and cold)	USPAT; US-PGPUB
22	L22	583	cold near6 (cap or capping)	USPAT; US-PGPUB
23	L23	7	19 and 22	USPAT; US-PGPUB
24	L24	555	19 and ("50" adj (percent or "%"))	USPAT; US-PGPUB
25	L25	121	24 and (bulk)	USPAT; US-PGPUB
26	L26	67	25 and aluminum	USPAT; US-PGPUB
27	L27	243	24 not (aluminum)	USPAT; US-PGPUB
28	L28	312	24 not 27	USPAT; US-PGPUB
29	L29	84	28 not (contact)	USPAT; US-PGPUB
30	L30	228	28 not 29	USPAT; US-PGPUB
31	L31	101	19 and (aluminum same (hot and cold))	USPAT; US-PGPUB
32	L32	0	31 and dcjhq893ht	USPAT; US-PGPUB
33	L33	22	31 and dc	USPAT; US-PGPUB
34	L34	18	((("4600658") or ("4786962") or ("4970176") or ("5108570") or ("5238868") or ("5242860") or ("5270255") or ("5288665") or ("5312512") or ("5371042") or ("5378660") or ("5380678") or ("5393565") or ("5434044") or ("5443995") or ("5470792") or ("5521120") or ("5804251")).PN.	USPAT; US-PGPUB
35	L35	2	34 and (DC)	USPAT; US-PGPUB
36	L36	9	34 and power	USPAT; US-PGPUB
37	L37	7	36 not 35	USPAT; US-PGPUB
38	L38	1	6217721.pn. and (DC or power)	USPAT; US-PGPUB
39	L39	27	19 and (IMP with (ti or tin or titanium))	USPAT; US-PGPUB
40	L40	1	5962923.pn.	USPAT; US-PGPUB
41	L41	0	40 and imp	USPAT; US-PGPUB
42	L42	0	40 and (metal adj plasma)	USPAT; US-PGPUB
43	L43	1	40 and (ionized)	USPAT; US-PGPUB

	Hits	Search Text	DBs	Time Stamp
1	48	"ti wetting" or "titanium wetting"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 15:58
2	38	("ti wetting" or "titanium wetting") and (aluminum)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 15:57
3	5	("ti wetting" or "titanium wetting") and (aluminum)) and imp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 15:59
4	33	("ti wetting" or "titanium wetting") and (aluminum)) not (("ti wetting" or "titanium wetting") and (aluminum)) and imp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 15:59
5	26	((("ti wetting" or "titanium wetting") and (aluminum)) not (("ti wetting" or "titanium wetting") and (aluminum)) and imp)) and (pvd or sputter\$3 or (ion\$5 adj metal\$5 adj plasma))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:05
6	1	US-6177350-B1.DID	DERWENT	2001/09/24 16:02
7	4520	((imp or (ion\$5 adj metal\$3 adj plasma) or (ion adj sputter\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:11
8	106	((imp or (ion\$5 adj metal\$3 adj plasma) or (ion adj sputter\$3)) near5 (ti or titanium or tin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:11
9	1	((imp or (ion\$5 adj metal\$3 adj plasma) or (ion adj sputter\$3)) and (((("ti wetting" or "titanium wetting") and (aluminum)) not (("ti wetting" or "titanium wetting") and (aluminum)) and imp)) and (pvd or sputter\$3 or (ion\$5 adj metal\$5 adj plasma)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:11
10	1	((imp or (ion\$5 adj metal\$3 adj plasma) or (ion adj sputter\$3)) and (((("ti wetting" or "titanium wetting") and (aluminum)) not (("ti wetting" or "titanium wetting") and (aluminum)) and imp))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:11
11	392614	wet or wetting	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:27
12	646	((wet or wetting) and ((imp or (ion\$5 adj metal\$3 adj plasma) or (ion adj sputter\$3)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:12
13	1	((wet or wetting) and ((imp or (ion\$5 adj metal\$3 adj plasma) or (ion adj sputter\$3))) and ((splash\$3 or resputter\$3) same (bias\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:21
14	7	((wet or wetting) and ((imp or (ion\$5 adj metal\$3 adj plasma) or (ion adj sputter\$3))) and ((splash\$3 or resputter\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:23
15	6	((((wet or wetting) and ((imp or (ion\$5 adj metal\$3 adj plasma) or (ion adj sputter\$3))) and ((splash\$3 or resputter\$3))) not (((wet or wetting) and ((imp or (ion\$5 adj metal\$3 adj plasma) or (ion adj sputter\$3))) and ((splash\$3 or resputter\$3) same (bias\$3))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:23
16	5	"0799903"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:23
17	9	"799903"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:23
18	9	"799903" not "0799903"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:25
19	1	US-6217721-B1.DID	DERWENT	2001/09/24 16:24
20	2	"6217721"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:25
21	1	"6217721" and chamber?	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:26
22	1	("6217721" and chamber?) and wet\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:26
23	1075610	((wet or wetting) or barrier or adhesion or lining or liner	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:28
24	21877	((wet or wetting) or barrier or adhesion or lining or liner) with (ti or titanium or tin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:28
25	310	((wet or wetting) or barrier or adhesion or lining or liner) same ((imp or (ion\$5 adj metal\$3 adj plasma) or (ion adj sputter\$3)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:29
26	7	((((wet or wetting) or barrier or adhesion or lining or liner) same ((imp or (ion\$5 adj metal\$3 adj plasma) or (ion adj sputter\$3))) and (resputter\$3 or re-sputter\$3 or splash\$3 or redeposit\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:53
27	1119	((wet or wetting) or barrier or adhesion or lining or liner) near7 (resputter\$3 or re-sputter\$3 or splash\$3 or redeposit\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 17:00
28	1	((((wet or wetting) or barrier or adhesion or lining or liner) near7 (resputter\$3 or re-sputter\$3 or splash\$3 or redeposit\$3)) and ((imp or (ion\$5 adj metal\$3 adj plasma) or (ion adj sputter\$3)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:33
29	10	((((wet or wetting) or barrier or adhesion or lining or liner) near7 (resputter\$3 or re-sputter\$3 or splash\$3 or redeposit\$3)) and 204/\$ ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:33
30	20	((((wet or wetting) or barrier or adhesion or lining or liner) near7 (resputter\$3 or re-sputter\$3 or splash\$3 or redeposit\$3)) and 438/\$ ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:34
31	18	(((((wet or wetting) or barrier or adhesion or lining or liner) near7 (resputter\$3 or re-sputter\$3 or splash\$3 or redeposit\$3)) and 438/\$ ccls.) not (((wet or wetting) or barrier or adhesion or lining or liner) near7 (resputter\$3 or re-sputter\$3 or splash\$3 or redeposit\$3)) and 204/\$ ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:34
32	59	((((wet or wetting) or barrier or adhesion or lining or liner) near7 (resputter\$3 or re-sputter\$3 or splash\$3 or redeposit\$3)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:38
33	21942	((wet or wetting) or barrier or adhesion or lining or liner) with (ti or titanium or tin or ((imp or (ion\$5 adj metal\$3 adj plasma) or (ion adj sputter\$3)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:39
34	1383	((wet or wetting) or barrier or adhesion or lining or liner) and ((imp or (ion\$5 adj metal\$3 adj plasma) or (ion adj sputter\$3)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:40
35	129	((((wet or wetting) or barrier or adhesion or lining or liner) and ((imp or (ion\$5 adj metal\$3 adj plasma) or (ion adj sputter\$3))) and 204/\$ ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:53

	Hits	Search Text	DBs	Time Stamp
36	0	6176983.pn. and (((wet or wetting) or barrier or adhesion or lining or liner) same ((imp or (ion\$5 adj metal\$3 adj plasma) or (ion adj sputter\$3))) and (resputter\$3 or re-sputter\$3 or splash\$3 or redeposit\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:53
37	1	6176983.pn. and (resputter\$3 or re-sputter\$3 or splash\$3 or redeposit\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:54
38	2	6176983.pn	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 16:59
39	37702	(resputter\$3 or re-sputter\$3 or splash\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 17:02
40	2429	((resputter\$3 or re-sputter\$3 or splash\$3) same ((wet or wetting) or barrier or adhesion or lining or liner)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 17:00
41	1447	((resputter\$3 or re-sputter\$3 or splash\$3) with ((wet or wetting) or barrier or adhesion or lining or liner)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 17:00
42	1010	((resputter\$3 or re-sputter\$3 or splash\$3) near7 ((wet or wetting) or barrier or adhesion or lining or liner)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 17:00
43	3	((resputter\$3 or re-sputter\$3 or splash\$3) near7 ((wet or wetting) or barrier or adhesion or lining or liner) and 204/192\$.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 17:01
44	11	((resputter\$3 or re-sputter\$3 or splash\$3) near7 ((wet or wetting) or barrier or adhesion or lining or liner) and (204/5.cccls. or 438/5.cccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 17:01
45	448	(resputter\$3 or re-sputter\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 17:02
46	28	((imp or (ion\$5 adj metal\$3 adj plasma) or (ion adj sputter\$3))) and ((resputter\$3 or re-sputter\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 17:17
47	13	("4756801") or ("4865712") or ("4963239") or ("4999098") or ("5126028") or ("5302266") or ("5303139") or ("5346600") or ("5510011") or ("5584974") or ("5770023") or ("5810963") or ("5858184").PN.	USPAT; US-PGPUB	2001/09/24 17:18
48	123	((substrate or wafer) near5 bias\$3) with (coverage or sidewall? or resputter\$3 or re-sputter\$3)	USPAT; US-PGPUB	2001/09/24 17:33
49	4	((substrate or wafer) near5 bias\$3) with (coverage or sidewall? or resputter\$3 or re-sputter\$3) and ("ti wetting" or "titanium wetting")	USPAT; US-PGPUB	2001/09/24 17:20
50	50	((substrate or wafer) near5 bias\$3) with (coverage or sidewall? or resputter\$3 or re-sputter\$3) and (barrier or wetting)	USPAT; US-PGPUB	2001/09/24 17:32
51	46	((substrate or wafer) near5 bias\$3) with (coverage or sidewall? or resputter\$3 or re-sputter\$3) and (barrier or wetting) not (((substrate or wafer) near5 bias\$3) with (coverage or sidewall? or resputter\$3 or re-sputter\$3) and ("ti wetting" or "titanium wetting"))	USPAT; US-PGPUB	2001/09/24 17:24
52	1539	(bias\$3) with (coverage or sidewall? or resputter\$3 or re-sputter\$3)	USPAT; US-PGPUB	2001/09/24 17:36
53	35	((bias\$3) with (coverage or sidewall? or resputter\$3 or re-sputter\$3) and wetting	USPAT; US-PGPUB	2001/09/24 17:35
54	281	(bias\$3) with (coverage or sidewall? or resputter\$3 or re-sputter\$3)	EPO; JPO; DERWENT; IBM TDB	2001/09/24 17:36
55	1	((bias\$3) with (coverage or sidewall? or resputter\$3 or re-sputter\$3) and wetting	EPO; JPO; DERWENT; IBM TDB	2001/09/24 17:36
56	49	((bias\$3) with (coverage or sidewall? or resputter\$3 or re-sputter\$3) and semiconductor	EPO; JPO; DERWENT; IBM TDB	2001/09/24 17:36
57	48	((bias\$3) with (coverage or sidewall? or resputter\$3 or re-sputter\$3) and semiconductor) not (((bias\$3) with (coverage or sidewall? or resputter\$3 or re-sputter\$3) and wetting)	EPO; JPO; DERWENT; IBM TDB	2001/09/24 17:48
58	333407	wetting or liner or lining	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 17:48
59	323837	(wetting or liner or lining) not semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 17:48
60	9570	(wetting or liner or lining) not ((wetting or liner or lining) not semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 17:49
61	67	((wetting or liner or lining) not ((wetting or liner or lining) not semiconductor)) and (bias\$3 with (sidewall? or coverage or resputter\$3 or re-sputter\$3 or splash\$3 or redeposit\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 18:01
62	2	6217721.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 18:01
63	0	6217721.pn. and imp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 18:01
64	0	6217721.pn. and (metal\$4 adj plasma)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 18:21
65	1	6217721.pn. and arc	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 18:31
66	1	6217721.pn. and (clean\$ or pre-clean\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/09/24 18:33